

**Features**

- Types up to 1000 V  $V_{RRM}$
- Ideal for printed circuit board
- Built-in printed circuit board stand-offs
- High temperature soldering guaranteed 265°C/ 10 seconds
- High case dielectric strength
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0

**Mechanical Data**

Case: Reliable low cost construction  
Weight: 0.065 oz, 2.2 g  
Mounting position: Any  
Terminals: Plated leads, solderable per MIL-STD-202, Method 208

**KBP Package**



**Maximum ratings, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	KBP206	KBP208	KBP210	Unit
Repetitive peak reverse voltage	$V_{RRM}$		600	800	1000	V
RMS reverse voltage	$V_{RMS}$		420	560	700	V
DC blocking voltage	$V_{DC}$		600	800	1000	V
Continuous forward current	$I_F$	$T_C \leq 50\text{ °C}$	2	2	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ °C}$ , $t_p = 8.3\text{ ms}$	60	60	60	A
Operating temperature	$T_j$		-50 to 150	-50 to 150	-50 to 150	°C
Storage temperature	$T_{stg}$		-50 to 150	-50 to 150	-50 to 150	°C

**Electrical characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	KBP206	KBP208	KBP210	Unit
Diode forward voltage	$V_F$	$I_F = 2\text{ A}$ , $T_j = 25\text{ °C}$	1.1	1.1	1.1	V
Reverse current	$I_R$	$V_R = 50\text{ V}$ , $T_j = 25\text{ °C}$	10	10	10	$\mu\text{A}$
		$V_R = 50\text{ V}$ , $T_j = 100\text{ °C}$	200	200	200	

**Thermal characteristics**

Thermal resistance, junction - case	$R_{thJL}$		25.0	25.0	25.0	°C/W
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